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### 2SJ0364 (2SJ364)

### Silicon P-channel junction FET

#### For analog switch circuits

#### ■ Features

- Low ON resistance
- Low-noise characteristics

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Gate-drain surrender voltage	V <sub>GDS</sub>	65	V	
Drain current	$I_D$	-20	mA	
Gate current	$I_G$	-10	mA	
Power dissipation	$P_{\mathrm{D}}$	150	mW	
Channel temperature	T <sub>ch</sub>	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	

#### Package

- Code
  - SMini3-G1
- Pin Name
  - 1: Source
  - 2: Drain
  - 3: Gate
- Marking Symbol: 4M

#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

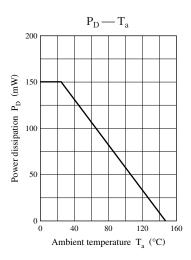
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Gate-drain surrender voltage	V <sub>GDS</sub>	$I_G = 10 \mu\text{A},  V_{DS} = 0$	65	0,		V
Drain-source current *	$I_{\mathrm{DSS}}$	$V_{DS} = -10 \text{ V}, V_{GS} = 0$	- 0.6	<i>)</i> -	-6.0	mA
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = 30 \text{ V}, V_{DS} = 0$	2.90		10	nA
Gate-source cutoff voltage	V <sub>GSC</sub>	$V_{DS} = -10 \text{ V}, I_D = -10 \mu A$		1.5	3.5	V
Forward transfer admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}, f = 1 \text{ kHz}$	1.8	2.5		mS
Short-circuit forward transfer capacitance (Common source)	C <sub>iss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		12		pF
Reverse transfer capacitance (Common source)	C <sub>rss</sub>	28 110 :		4		pF
Drain-source ON resistance	R <sub>DS(on)</sub>	$V_{DS} = -10 \text{ mV}, V_{GS} = 0$		300		Ω

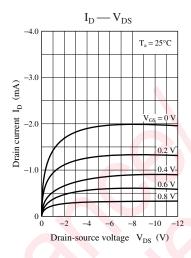
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

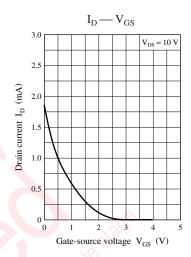
- 2. Observe precautions for handling. Electrostatic sensitive devices.
- 3. \*: Rank classification

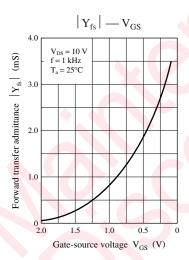
Rank	Р	Q	R
I <sub>DSS</sub> (mA)	− 0.6 to −1.5	-1.0 to -3.0	-2.5 to -6.0

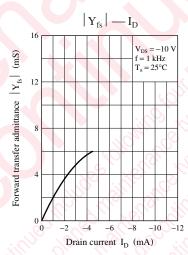
Note) The part number in the parenthesis shows conventional part number.

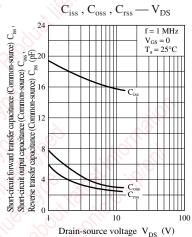






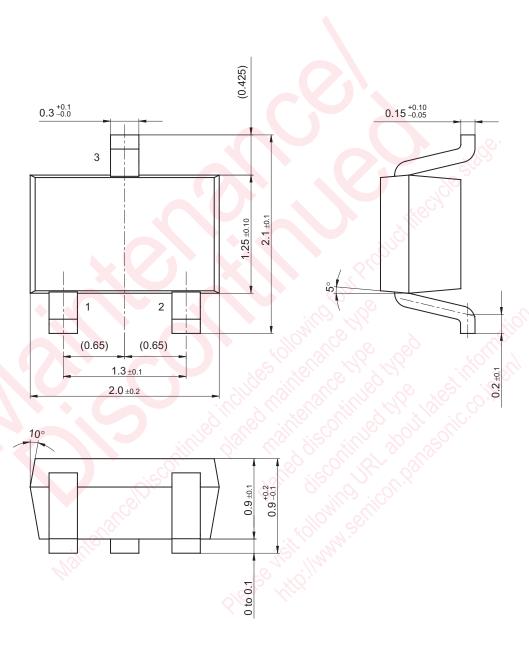






2 SJF00003CED

SMini3-G1 Unit: mm



SJF00003CED 3

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